

2021.08.27 New Products Release

**Sales Release of “Plasma Laser Repair Equipment”
for Yield Improvement in Semiconductor Packaging Process (PAT. PEND.)**

We, AIMECHATEC, Ltd. (Head Office: Koyodai, Ryugasaki-shi, Ibaraki-pref. President: Isao Abe) are pleased to announce that New Product “Plasma Laser Repair Equipment ALR-04G -P4” will be released as our new proposal for Semiconductor Business.

This equipment has been developed for Yield Improvement in Semiconductor Packaging Process, and enabled Inspection and Repair for Solder Ball Drop Defects being occurred during Reflow and De-Flux Cleaning Process after Ball Mounting. As the Process Flow, New Solder Balls are mounted on the Pads of which Balls are dropped off and soldered by Plasma and Laser technologies.

The Solder Ball Drop Defects make a big impact on Yield Deterioration in Semiconductor Packaging Process. However, it becomes possible to increase Non-defective Rate and further improve Yield through repairing with this equipment.

Demands for Semiconductor Packages such as Data Center, Mobile Devices and In-vehicle applications have been expanding in the background of 5G Communication, Big Data, IoT and AI. At the same time, Stable Quality and further Yield Improvement are required. The needs for major Advanced Semiconductor Packages such as FCBGA, MCU/MPU, 2.5/3D, and Fan-out are extremely higher, and then this new equipment with Yield Improvement can be realized, has been considered for customers’ applications and their future planning.

We will continue to contribute to society by improving more convenient and affluent lifestyles through our technological innovations for manufacturing processes.

Contact:

AIMECHATEC, Ltd.

Sales Dept. TEL:0297-62-9119

https://www.ai-mech.com/wp_en/newproducts/



Plasma Laser Repair Equipment